

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|---|------------|-------|-------------------------|---------|
| Die | N/A | Silicon Carbide (SiC) | 409-21-2 | 0.05 | 100.0 | 1.02 |
| Subtotal | | | | 0.05 | 100 | 1.02 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.08 | 100.0 | 1.7 |
| Subtotal | | | | 0.08 | 100 | 1.7 |
| Solder Wire | Lead alloy | Tin (Sn) | 7440-31-5 | 0 | 2.0 | 0.02 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0 | 2.5 | 0.03 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.05 | 95.5 | 1.1 |
| | Subtotal | | | 0.05 | 100 | 1.15 |
| Post-plating | Lead alloy | Tin (Sn) | 7440-31-5 | 0.75 | 100.0 | 15 |
| Subtotal | | | | 0.75 | 100 | 15 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.02 | 0.03 | 0.43 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.07 | 0.1 | 1.42 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 70.23 | 99.67 | 1412.32 |
| | Copper alloy | Silver (Ag) | 7440-22-4 | 0.14 | 0.2 | 2.83 |
| | Subtotal | | | 70.46 | 100 | 1417 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 1.86 | 6.5 | 37.38 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 4.58 | 16.0 | 92 |
| | Filler | Silica fused | 60676-86-0 | 20.3 | 71.0 | 408.25 |
| | Flame retardant | Metal hydroxide | | 1.86 | 6.5 | 37.38 |
| | Subtotal | | | 28.6 | 100 | 575.01 |
| Total | | | | 99.99 | 100 | 2010.88 |

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